

# **Revision History**

Date	Rev. No.	Page	Summary
17.01.2025	0	ALL	FIRST ISSUE

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# \* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amo rphous silicon TFT as a switching device. This module is composed of a Transmissive type TFT-LCD Panel, driver circuit,back-light unit. The resolution of a 2.76 " TFT-LCD contains 480x480 pixels, and can display up to 16.7M colors.

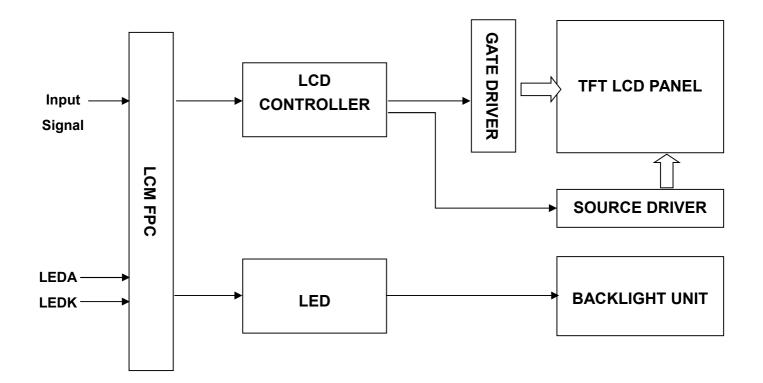
# \* Features

General Information Items	Specification	l lait	Nata
BBV	Main Panel	– Unit	Note
Display Area (AA)	70.13 x 70.13 (2.76 Inch)	mm	-
Driver Element	TFT Active Matrix	-	-
Display Colors	16.7 Million	colors	-
Number of Pixels	480 x RGB x480	dots	-
Pixel Arrangement	RGB Vertical Stripe	-	-
Pixel Pitch	0.1461 x 0.1461	mm	-
Viewing Angle	ALL	o'clock	-
Controller IC	ST7701S (Sitronix)	-	-
LCM Interface	2-Lane MIPI	-	-
Display Mode	IPS, Transmissive / Normally Black	-	-
Operating Temperature	-20°C ~ +70°C	°C	-
Storage Temperature	-30°C ~ +80°C	°C	-

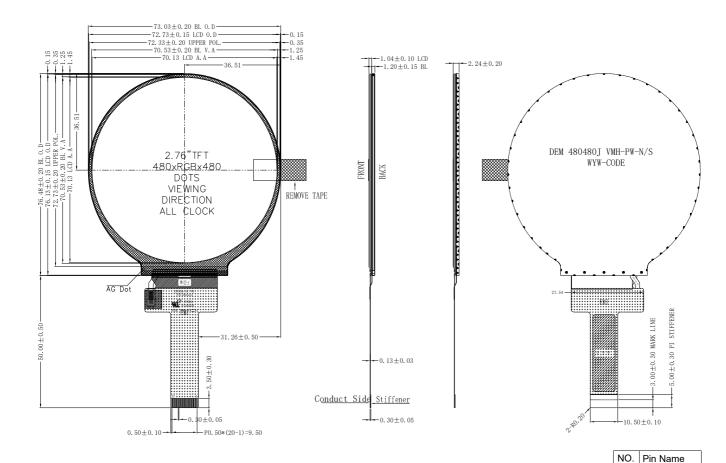
# \* Mechanical Information

	ltem	Min.	Тур.	Max.	Unit	Note
	Horizontal(H)	-	73.03	-	mm	-
Module Size	Vertical(V)	-	76.48	-	mm	-
SIZE	Depth(D)	-	2.24	-	mm	-
	Weight		21	-	g	-

# 1. Block Diagram

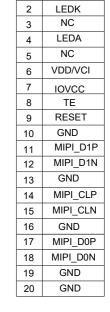


# 2. Outline Dimension



Note: The opening of top case must less than LCD POL 0.3mm at least, the LCD V.A is the Recommended opening of Lens.





NC

1

−0 LED− K

К

# Input Terminal Pin Assignment

NO	SYMBOL	DISCRIPTION	I/O
1	NC		
2	LEDK	Cathode pin of backlight.	Р
3	NC		
4	LEDA	Anode pin of backlight.	Р
5	NC		
6	VDD/VCI	Supply Voltage (3.3V).	Р
7	IOVCC	I/O power supply voltage.	Р
8	TE	-Tearing effect output Leave the pin to open when not in use.	0
9	RESET	- The external reset input. Initializes the chip with a low input. Be sure to execute a power-on reset after supplying power.	I
10	GND	Ground.	Р
11	MIPI_D1P		I/O
12	MIPI_D1N	MIPI DSI differential data pair (DSI-Dn+/-).	I/O
13	GND	Ground.	Р
14	MIPI_CLP		I
15	MIPI_CLN	MIPI DSI differential clock pair (DSI-CLK+/-).	I
16	GND	Ground.	Р
17	MIPI_D0P	MIDI DSI differential data pair (DSI Dp. / )	I/O
18	MIPI_D0N	MIPI DSI differential data pair (DSI-Dn+/-).	I/O
19	GND	Ground.	Р
20	GND	Ground.	Р

# 4. LCD Optical Characteristics

# 4.1 Optical Specification

Item		Symbol	Condition	Min.	Тур.	Max.	Unit.	Note
Contrast R	atio	CR		1000	1500			*(1)(2)
Response Time	Rising Falling	T <sub>R+</sub> T <sub>F</sub>			35	40	msec	*(1)(3)
Color Gar	nut	S(%)		55	59		%	*
		Wx	Θ=0	0.237	0.277	0.317		CA-310
	White	W <sub>Y</sub>	Normal	0.238	0.278	0.318		Test
	Red	Rx	Viewing Angle	0.572	0.612	0.652		
Color Filter		R <sub>Y</sub>		0.291	0.331	0.371		
Chromacicity	Green	Gx		0.266	0.306	0.346		
		G <sub>Y</sub>		0.511	0.551	0.591		
		B <sub>X</sub>		0.109	0.149	0.189		
	Blue	B <sub>Y</sub>		0.015	0.055	0.095		
		ΘL		80	85			*(1)(4)
Viewing	Hor.	ΘR		80	85			
Angle		ΘU	CR>10	80	85			
	Ver.	ΘD		80	85			
Option View D	irection			ŀ	ALL .			

\*The data comes from the LCD specification.

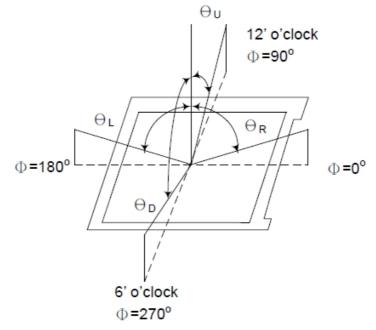
## **Measuring Condition**

Measuring surrounding: dark room Ambient temperature: 25°C±2°C 15min. warm-up time.

## **Measuring Equipment**

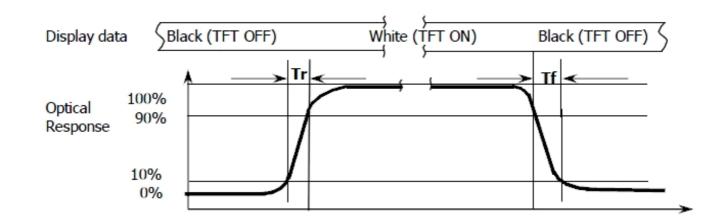
FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

Note (1): Definition of Viewing Angle :



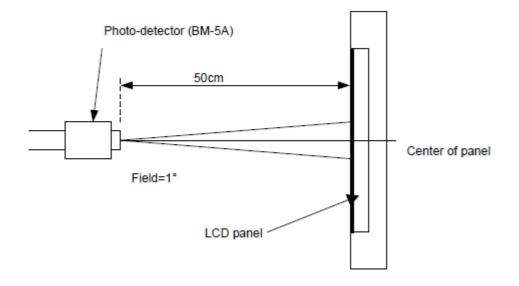
Note (2): Definition of Contrast Ratio(CR) :measured at the center point of panel

CR = Luminance with all pixels white Luminance with all pixels black



Note (3): Response Time

Note (4): Definition of optical measurement setup



# **5. Electrical Characteristics**

## 5.1 Absolute Maximum Rating

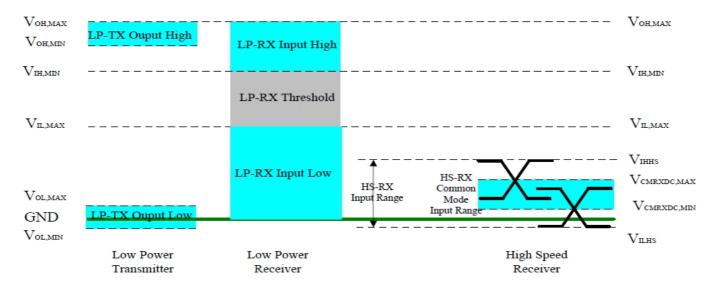
Characteristics	Symbol	Min.	Max.	Unit	Note
Digital Supply Voltage	VCI	-0.3	4.6	V	Note1
Digital Interface Supply	IOVCC	-0.3	4.6	V	-
Operating Temperature	T <sub>OP</sub>	-20	+70	°C	-
Storage Temperature	Tst	-30	+80	°C	_

NOTE1: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

## **5.2 DC Electrical Characteristics**

Characteristics	Symbol	Min.	Тур.	Max.	Unit	Note
Digital Supply Voltage	VCI	2.5	3.3	3.6	V	-
Digital Interface Supply Voltage	IOVCC	1.65	1.8	3.3	V	-
Normal Mode Current Consumption	ICC		16	32	mA	-
Differential Input High Threshold Voltage	VIT+		0	50	mV	
Differential Input Low Threshold Voltage	VIT-	-50	0		mV	MIPI_CLK MIPI_Data
Single-ended Receiver Input Operation Voltage Range	VIR	0.5		1.2	V	

## **5.3 MIPI DC Electrical Characteristics**



Parameter	Symbol		Unit					
Farameter	Symbol	MIN	TYP	MAX	Unit			
Operation ∀oltage for MIPI Receiver								
Low power mode operating voltage	Vlph	1.1	1.2	1.3	V			
MIPI Character	ristics for High	n Speed Rece	iver	•				
Single-ended input low voltage	V ILHS	-40	-	-	m∨			
Single-ended input high voltage	V inns	-	-	460	m∨			
Common-mode voltage	VCMRXDC	70	-	330	m∨			
Differential input impedance	ZID	80	100	125	ohm			
MIPI Charac	teristics for Lo	w Power Mod	le	•				
Pad signal voltage range	VI	-50	-	1350	m∨			
Logic 0 input threshold	VIL	0-	-	550	m∨			
Logic 1 input threshold	∨н	880	-	1350	m∨			
Output low level	Vol	-50	-	50	m∨			
Output high level	√он	1.1	1.2	1.3	V			

## 5.4 LED Backlight Characteristics

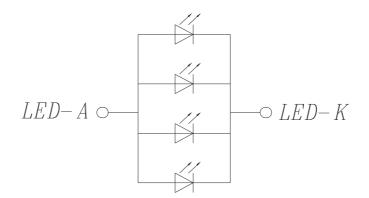
Item	Symbol	Min.	Тур.	Max.	Unit	Note
Forward Current	lF		80		mA	
Forward Voltage	VF	5.4		6.6	V	
LCM Luminance	LV	450	500		cd/m2	Note3
LED Lifetime	Hr	50000			Hour	Note1,2
Uniformity	Avg	80			%	Note3

The backlight system is edge-lighting type with 4 chips LED

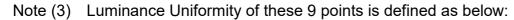
Note1: LED life time (Hr) can be defined as the time in which it continues to operate under the condition: Ta=25°C±3°C, typical IL value indicated in the above table until the brightness becomes less than 50%.

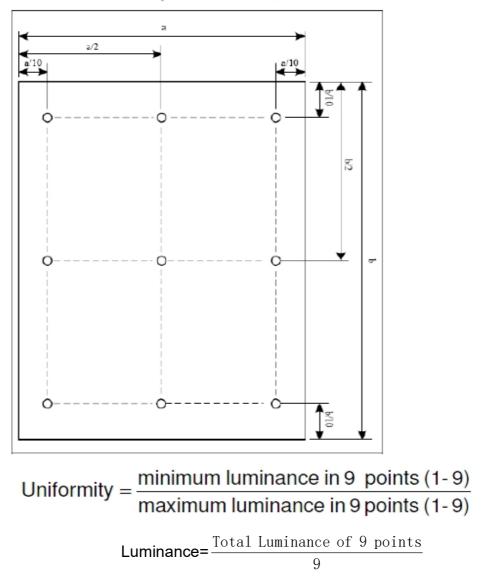
Note 2: The "LED life time" is defined as the module brightness decrease to 50% original brightness at Ta=25°C and IL=80mA. The LED lifetime could be decreased if operating IL is larger than 80mA.

The constant current driving method is suggested.



CIRCUIT DIAGRAM





# 6. AC Characteristics

## 6.1 MIPI Interface Characteristics:

#### 6.1.1 High Speed Mode

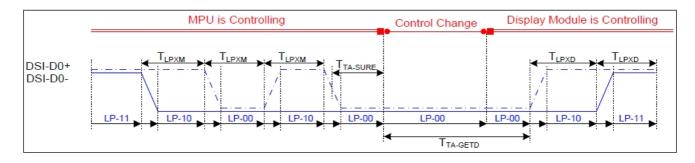


#### \*DSI clock channel timing

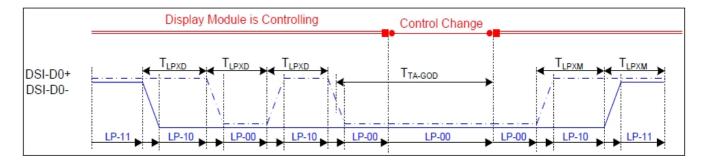
Signal	Symbol	Parameter	MIN	MAX	Unit	Description
DSI-CLK+/-	2xUI <sub>INSTA</sub>	Double UI instantaneous	4	25	ns	
DSI-CLK+/-	UI <sub>INSTA</sub> UI <sub>INSTB</sub>	UI instantaneous halfs	2	12.5	ns	UI = UI <sub>INSTA</sub> = UI <sub>INSTB</sub>
DSI-Dn+/-	tDS	Data to clock setup time	0.15	-	UI	
DSI-Dn+/-	tDH	Data to clock hold time	0.15	-	UI	

\* MIPI Interface-High Speed Mode Timing Characteristics

#### 6.1.2 Low Power Mode



#### \* Bus Turnaround (BTA) from display module to MPU Timing

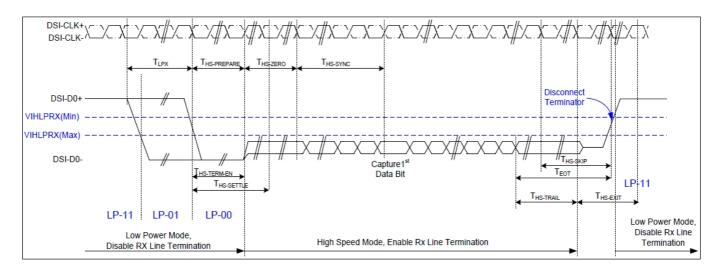


## \*Bus Turnaround (BTA) from MPU to display module Timing

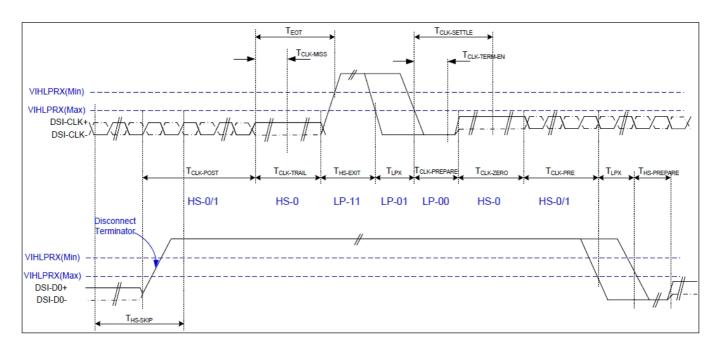
Signal	Symbol	Parameter	Parameter MIN M		Unit	Description	
		Length of LP-00,LP-01,					
DSI-D0+/-	TLPXM	LP-10 or LP-11 periods	50	75	ns	Input	
		MPU→Display Module					
		Length of LP-00,LP-01,					
DSI-D0+/-	TLPXD	LP-10 or LP-11 periods	50	75	ns	Output	
		MPU→Display Module					
DSI-D0+/-	TTA-SURED	Time-out before the MPU	TLPXD	2xT <sub>LP</sub>	ns	Output	
DSI-D0+/-	TIA-SURED	start driving	LPXD	XD	ns	Output	
DSI-D0+/-		Time to drive LP-00 by	Ev.T			lanut	
DSI-D0+/-	TTA-GETD	display module	521	LPXD	ns	Input	
		Time to drive LP-00 after	4xTLexp			Output	
DSI-D0+/-	TTA-GOD	turnaround request-MPU	4X1	LPXD	ns	Output	

\*MIPI Interface Low Power Mode Timing Characteristics

#### 6.1.3 Burst Mode



\*Data lanes-Low Power Mode to/from High Speed Mode Timing



#### \*Clock lanes- High Speed Mode to/from Low Power Mode Timing

Signal	Symbol	Parameter	MIN	МАХ	Unit	Description
Low Power Mode to High Speed Mode Timing						
DSI-Dn+/-	TLPX	Length of any low power state period	50	-	ns	Input
DSI-Dn+/-	THS-PREPARE	Time to drive LP-00 to prepare for HS transmission	40+4 UI	85+6 UI	ns	Input
DSI-Dn+/-	THS-TERM-EN	Time to enable data receiver line termination measured from when Dn crosses VILMAX	-	35+4 UI	ns	Input
DSI-Dn+/-	THS-PREPARE + THS-ZERO	THS-PREPARE + time to drive HS-0 before the sync sequence	140+ 10UI	-	ns	Input
	H	High Speed Mode to Low Power Mo	ode Timir	ng		
DSI-Dn+/-	THS-SKIP	Time-out at display module to ignore transition period of EoT	40	55+4 UI	ns	Input
DSI-Dn+/-	THS-EXIT	Time to drive LP-11 after HS burst	100	-	ns	Input
DSI-Dn+/-	THS-TRAIL	Time to drive flipped differential state after last payload data bit of a HS transmission burst	60+4 UI	-	ns	Input
	Hig	h Speed Mode to/from Low Power	Mode Ti	ming		
DSI-CLK+/-	TCLK-POS	Time that the MPU shall continue sending HS clock after the last associated data lane has transition to LP mode	60+5 2UI	-	ns	Input
DSI-CLK+/-	TCLK-TRAIL	Time to drive HS differential state after last payload clock bit of a HS transmission burst	60	-	ns	Input
DSI-CLK+/-	THS-EXIT	Time to drive LP-11 after HS burst	100	-	ns	Input
DSI-CLK+/-	TCLK-PREPARE	Time to drive LP-00 to prepare for HS transmission	38	95	ns	Input
DSI-CLK+/-	TCLK-TERM-EN	Time-out at clock lan display module to enable HS transmission	-	38	ns	Input
DSI-CLK+/-	TCLK-PREPARE + TCLK-ZERO	Minimum lead HS-0 drive period before starting clock	300	-	ns	Input
DSI-CLK+/-	TCLK-PRE	Time that the HS clock shall be driven prior to any associated data lane beginning the transition from LP to HS mode	8UI	-	ns	Input
DSI-CLK+/-	TEOT	Time form start of TCLK-TRAIL period to start of LP-11 state	-	105n s+12 UI	ns	Input

## 6.2 Reset Timing

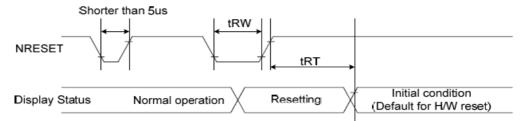


Figure 102 Reset Timing

#### Table 41 Reset Timing

Signal	Symbol	Parameter	Min	Max	Unit
	tRW	Reset pulse duration	10		us
RESX	tRT Reset of	Boost concol		5(note 1,5)	ms
	IKI	Reset cancel		120 (note 1,6,7)	ms

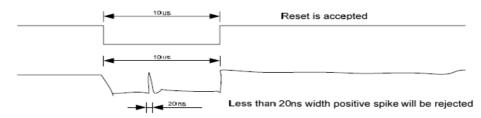
Note:

- The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from OTP to registers. This loading is done every time when there is H/W reset cancel time (tRT) within 5 ms after a rising edge of RESX.
- Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the Table 43.

#### Table 42 Reset Descript

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

- 3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out mode. The display remains the blank state in Sleep In mode.) and then return to Default condition for Hardware Reset.
- 4. Spike Rejection also applies during a valid reset pulse as shown below:



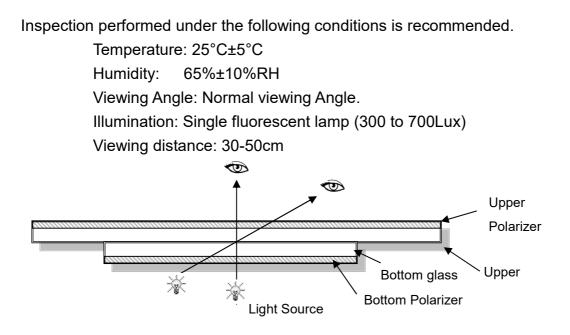
#### Figure 103 Positive Noise Pulse during Reset Low

- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

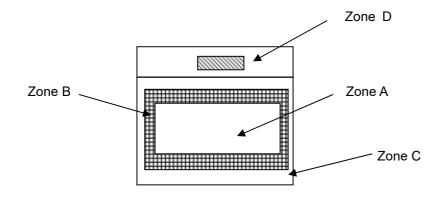
# 7. LCD Module Out-Going Quality Level

## 7.1 VISUAL & FUNCTION INSPECTION STANDARD

## 7.1.1 Inspection Conditions



## 7.1.2 Definition



Zone A : Effective Viewing Area(Character or Digit can be seen)

Zone B : Viewing Area except Zone A

Zone C : Outside (Zone A+Zone B) which can not be seen after assembly by customer

Zone D : IC Bonding Area

Note: As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer

# 7.1.3 Sampling Plan

According to GB/T 2828-2012, normal inspection, Class II AQL:

Major Defect	Minor Defect
0.65	1.5

LCD: Liquid Crystal Display, LCM: Liquid Crystal Module,

No	Items to be inspected	Criteria	Classification of defects
		1) No display, Open or miss line	
1	Functional defects	2) Display abnormally, Short	
		3) Backlight no lighting, abnormal lighting.	
		etc	Major
2	Missing	Missing components and etc	,
		Overall outline dimension beyond the	
3	Outline dimension	drawing is not allowed, deformation etc	
4	Color tone	Color unevenness, refer to limited sample	
		Light dot,Dim spot,(Note1)	
5	Spot/Line defect	Polarizer Air Bubble,	
		Polarizer accidented spot etc.	Minor
6	Soldering appearance	Good soldering , Peeling off is not allowed	
0	Soldering appearance	etc.	
7	LCD/Polarizer	Black/White spot/line, scratch, crack, etc.	

- Note: a) Light dot: Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern.
  - b) Dim dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green, blue picture.

# 7.1.4 Criteria (Visual)

Number	Items	Criteria(mm)				
<ul> <li>1.0 LCD</li> <li>Crack/Broken</li> <li>NOTE:</li> <li>X: Length</li> <li>Y: Width</li> <li>Z: Height</li> <li>L: Length of ITO,</li> </ul>	(1) The edge of LCD broken					
		X Y Z				
T: Height of LCD		≤3.0mm <pre><inner border="" line="" of<br="">the seal</inner></pre>				
	(2)LCD corner broken	XYZ $\leq 3.0$ mm $\leq L$ $\leq T$				
	(3) LCD crack	Crack Not allowed				

# **Product Specification**

	Spot defect	⊕ light dot ( black	x/white spot , pinhole, stain,etc.)				
		Zone	Acce	Acceptable Qty			
	↓ Y	Size (mm)	А	В	С		
2.0		Ф≤0.15	Ignore				
2.0	X	0.15<Φ≤0.25	3(distance≧6mm)		Ignore		
	Φ=(X+Y)/2	0.25<Φ≤0.4	2(distance≧6mm)		Ignore		
	$\Psi = (X + 1)/2$	Φ>0.4	0				
		② Dim spot ( light le	eakage、dent、dark:	spot, etc)			
		Zone	Acce	ptable Qty			
		Size (mm)	A	В	С		
		Φ≤0.15	Ignore		<b>L</b>		
		0.15<Φ≤0.25			Ignore		
		0.25<Φ≤0.4	2( distance $\geq 6$ mm)	)	5		
		Φ>0.4 ③ Polarizer accider	0 Ned spot				
				ptable Qty			
		Zone	A	B	С		
		Size (mm)		D	C		
		Φ≤0.2	Ignore				
		0.2<Φ≤0.5	2( distance≧	o <b>mm)</b>	Ignore		
		Φ>0.5	0				
		④Polarizer Bubble					
		Zone	Acce	eptable Qty			
		Size (mm)	A	В	С		
		Φ≤0.2	Ignore				
		0.2<Ф≤0.4	3(distance≧6mm)				Ignore
		Φ>0.4	0				

3.0	LCD Pixel defect	Pixel bad poi	nts			
		Item	Zone A	Acceptable Qty		
			Random	N≤2		
		Bright dot	2 dots adjacent	N≤0		
			3 dots adjacent	N≤0		
			Random	N≤2		
		Dark dot	2 dots adjacent	N≤0		
			3 dots adjacent	N≤0		
		Distance	<ol> <li>Minimum Distance Between Bright dots.</li> <li>Minimum Distance Between dark dots</li> <li>Minimum Distance Between dark and bright dot.</li> </ol>	5mm		
		Total bright a	Total bright and dark dot N≤4			
		Note:				
		A) Bright dot: Dots appear bright and unchanged in size in which				
		LCD panel is displaying under black pattern.				
		B) Dark dot: Dots appear dark and unchanged in size in which LCD				
		panel is displaying under pure red, green, blue picture.				
		C) 2 dot adja Picture:	icent = 1 pair = 2 dots			
		2 dot adjacent 2 dot adjacen				
		2 dot adjacer	nt (vertical) 2 dot adjacent (	slant)		

	Line defect (LCD							
	/Polarizer backlight	Midth(mm)	Length(m	n Acceptable Qty		ty		
	black/white line,	Width(mm)	m)	А	В	С		
	scratch, stain)	Ф≤0.03	Ignore	Ignore				
4.0		0.03 <w≤0.04< td=""><td>L≤3.0</td><td>N≤2</td><td></td><td colspan="2">Ignore</td></w≤0.04<>	L≤3.0	N≤2		Ignore		
	W: width, L : length	0.04 <w≤0.05< td=""><td>L≤2.0</td><td>N≤1</td><td></td><td></td></w≤0.05<>	L≤2.0	N≤1				
	N : Count	W>0.05	W>0.05 Define as spot defect					
	Electronic Compo	Not allow missing par smatch, The positive				lder joint,mi		
5.0	nents SMT.	F						
Display color& B 1. Color: Measuring the color coordinates, The measure rd according to the datasheet or samples.				ement standa				
6.0	rightness.	2. Brightness: Measuring the brightness of White screen, The meas urement standard according to the datasheet or Samples.						
LCD Mura/Wavin Not visible through 5% ND filter in 50% gray or judge to e if necessary.				oy limit sampl				
7.0	g/	-						
	Hot spot							

## Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed

# 8. Reliability Test Result

Item	Condition	Inspection after test
High Temperature Operating	+70°C,96h	
Low Temperature Operating	-20°C, 96h	
High Temperature Storage	+80°C, 96h	Inspection after 2~4hours
Low Temperature Storage	-30°C, 96h	storage at room
High Temperature & High	+60°C, 90% RH ,96h.	temperature, the sample
Humidity Operating	+00 C, 90 % RT ,901.	shall be free from
Thermal Shock	-10°C,30 min ↔ +60°C, 30 min,	defects:
(Non-operation)	Change time: 5min 20CYC.	1. Air bubble in the LCD;
		2. Non-display;
	C=150pF, R=330, 5points/panel	3. Missing segments/line;
ESD test	Air:±8kV, 5times; Contact:±6kV, 5 times;	4. Glass crack;
	(Environment: 15°C~35°C, 30%~60%).	5. Current IDD is twice
	Frequency range: 10~55Hz, Stroke:1.5mm	higher than initial value.
Vibration (Non-operation)	Sweep:10Hz~55Hz~10Hz 2 hours for each direction	5
	of X.Y.Z. (6 hours for total) (Package condition).	
Box Drop Test	1 Corner 3 Edges 6 faces, 80cm(MEDIUM BOX)	

Remark:

- 1. The test samples should be applied to only one test item.
- 2. Sample size for each test item is 5~10pcs.
- 3. For Damp Proof Test, Pure water (Resistance >  $10M\Omega$ ) should be used.
- 4. In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.
- 5. Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.
- 6. The color fading mura of polarizing filter should not care.

# 9. Cautions and Handling Precautions

## 9.1 Handling and Operating the Module

- (1) When the module is assembled, it should be attached to the system firmly.
  - Do not warp or twist the module during assembly work.
- (2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- (3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- (4) Do not allow drops of water or chemicals to remain on the display surface.

If you have the droplets for a long time, staining and discoloration may occur.

- (5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- (6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.

Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.

- (7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- (8) Protect the module from static; it may cause damage to the CMOS ICs.
- (9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (10) Do not disassemble the module.
- (11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- (12) Pins of I/F connector shall not be touched directly with bare hands.
- (13) Do not connect, disconnect the module in the "Power ON" condition.
- (14) Power supply should always be turned on/off by the item 6.1 Power On Sequence &6.2 Power Off Sequence

## 9.2 Storage and Transportation.

- (1) Do not leave the panel in high temperature, and high humidity for a long time.
   It is highly recommended to store the module with temperature from 0°C to 35°C and relative humidity of less than 70%
- (2) Do not store the TFT-LCD module in direct sunlight.
- (3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- (4) It is recommended that the modules should be stored under a condition where no condensation is allowed.Formation of dewdrops may cause an abnormal operation or a failure of the module.In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- (5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.